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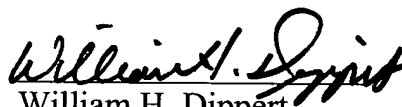
Attorney Docket: 501010.20522
Today's Date: October 25, 2002
Serial No. 10/045,651
Filing Date: November 7, 2001
For: MULTI-LAYER PRINTED CIRCUIT BOARD FABRICATION
SYSTEM AND METHOD

FIRST CLASS MAILING CERTIFICATE

FIRST CLASS MAIL

Deposited: October 25, 2002

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